

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TLF50251EL	**Issued**	28. August 2013
MA#	MA001056006		
Package	PG-SSOP-14-3	**Weight***	82.98 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.797	2.17	2.17	21662	21662
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.689	0.83		8304	
	non noble metal	copper	7440-50-8	27.978	33.72	34.60	337162	345985
wire	noble metal	gold	7440-57-5	0.168	0.20	0.20	2029	2029
encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1203	
	plastics	epoxy resin	-	4.591	5.53		55331	
	inorganic material	silicondioxide	60676-86-0	45.215	54.48	60.13	544885	601419
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11763	11763
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9251	9251
glue	plastics	epoxy resin	-	0.164	0.20		1973	
	noble metal	silver	7440-22-4	0.491	0.59	0.79	5918	7891
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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